Materials Declaration

Package	SOT 66
Body Size	--
LeadCount	6
Option	Pb-free

Molding Compound

Item	% of Compound	Weight (g)	PPM
SiO2	79.0	1.30 E-03	449862
Resin	18.0	2.95 E-04	102500
Sb2O3	1.8	2.95 E-05	10250
Brominated epoxy	1.0	1.64 E-05	5694
Carbon Black	0.2	3.28 E-06	1139
Subtotal		1.64 E-03	569446

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	96.33	9.34 E-04	324446
Fe	2.26	2.19 E-05	7598
Ni	1.15	1.12 E-05	3873
Zn	0.13	1.21 E-06	421
Pd	0.10	9.70 E-07	337
P	0.02	2.33 E-07	81
Au	0.02	1.46 E-07	51
Subtotal		9.70 E-04	336806

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	100	3.00 E-05	10416

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	5.00 E-05	17359

Chip

	% of Chip	Weight (g)	PPM
Si	100	1.60 E-04	55556

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Epoxy Resin	31	9.30 E-06	3229
Metal Oxide	31	9.30 E-06	3229
Glycol Ethers	22	6.60 E-06	2292
Silica	8	2.40 E-06	833
Curing agent & hardener	8	2.40 E-06	833
Subtotal		3.00 E-05	10417

Molding Compound

Item	PPM	Method
Pb	Not Detected	EPA Method 3051A/3052. ICP-OES
Cd	Not Detected	EPA Method 3051A/3052. ICP-OES
Hg	Not Detected	EPA Method 3051A/3052. ICP-OES
Cr+6	Not Detected	EPA Method 3060A & 7196A. UV-VIS
PBB	Not Detected	EPA Method 3540C/3550C. GC/MS.
PBDE	Not Detected	EPA Method 3540C/3550C. GC/MS.

Die Attach Paste

Item	PPM	Method
Pb	Not Detected	EPA Method 3051. ICP-AES.
Cd	Not Detected	EPA Method 3051. ICP-AES.
Hg	Not Detected	EPA Method 3051. ICP-AES.
Cr+6	Not Detected	EPA Method 3060A & 7196A. UV-VIS
PBB	Not Detected	EPA Method 3540C/3550C. GC/MS.
PBDE	Not Detected	EPA Method 3540C/3550C. GC/MS.

Package Totals

Weight (g)	PPM
2.88 E-03	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability tc
any inaccuracy of such information.

ANALOG DEVICES

ADI Proprietary